



JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

TO-126K Plastic-Encapsulate Thyristors

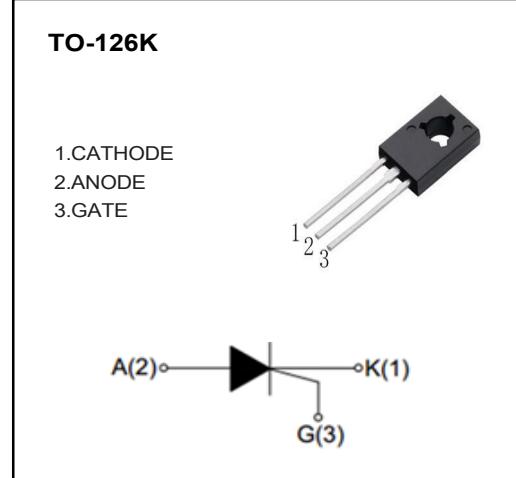
CS030E Sensitive Gate SCRs

MAIN CHARACTERISTICS

$I_{T(AV)}$	2A
V_{DRM}/V_{RRM}	600V
I_{GT}	200μA

FEATURES

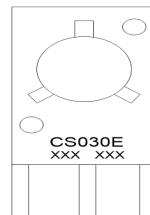
- PNPN 4-layer Structure SCRs
- Mesa Glass Passivated Technology
- Multi Layers Metal Electrodes
- Sensitive gate trigger



APPLICATIONS

- Pulse Igniter
- LED Controller
- Coffee Machine

MARKING



CS030E:Part Number
XXX:Internal Code

ABSOLUTE RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test condition	Value	Unit
V_{DRM}/ V_{RRM}	Repetitive peak off-state voltage	$T_j=25^\circ\text{C}$	600	V
$I_{T(AV)}$	Average on-state current	TO-126K($T_c \leq 80^\circ\text{C}$)	2	A
$I_{T(RMS)}$	RMS on-state current	TO-126K($T_c \leq 80^\circ\text{C}$), Fig. 1,2	3	A
I_{TSM}	Non repetitive surge peak on-state current	Full sine wave , $T_j(\text{init})=25^\circ\text{C}$, $tp=20\text{ms}$; Fig. 3,5	20	A
I^2t	I^2t value	$tp=10\text{ms}$	2	A^2s
di/dt	Critical rate of rise of on-state current	$I_G=2*I_{GT}$, $tr \leq 10\text{ns}$, $F=120\text{Hz}$, $T_j=110^\circ\text{C}$	50	$\text{A}/\mu\text{s}$
I_{GM}	Peak gate current	$tp=20\mu\text{s}$, $T_j=110^\circ\text{C}$	0.2	A
$P_{G(AV)}$	Average gate power	$T_j=110^\circ\text{C}$	0.1	W
T_{STG}	Storage temperature		-40~+150	$^\circ\text{C}$
T_j	Operating junction temperature		-40~+110	

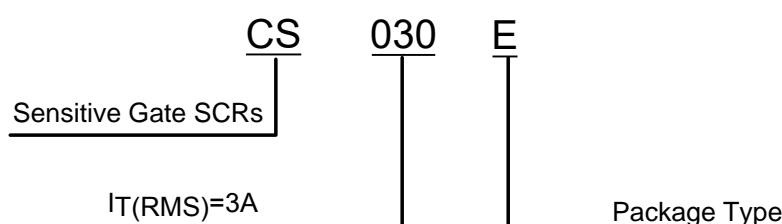
ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test condition	Value			Unit
			Min	Nom	Max	
I_{GT}	Gate trigger current	$V_D=6\text{V}$, $R_L=100\Omega$, $R_{GK}=1\text{k}\Omega$ Fig. 6	10	-	200	μA
V_{GT}	Gate trigger voltage	$V_D=12\text{V}$, $R_L=100\Omega$, $R_{GK}=1\text{k}\Omega$	-	-	0.8	V
V_{GD}	Non-triggering gate voltage	$V_D=1/2V_{DRM}$, $R_{GK}=1\text{k}\Omega$, $T_j=110^\circ\text{C}$	0.2	-	-	V
I_H	Holding current	$V_D=24\text{V}$, $R_{GK}=1\text{k}\Omega$, $I_{TM}=4\text{A}$, $T_j=25^\circ\text{C}$, Fig. 6	-	1	3	mA
I_L	Latching current	$I_G=1.2I_{GT}$, Fig. 6	-	-	4	mA
dV_D/dt	Critical rate of rise of off-state	$V_D=67\%V_{DRM}$, $R_{GK}=1\text{k}\Omega$, $T_j=110^\circ\text{C}$	10	-	-	V/ μs
V_{TM}	On-state Voltage	$I_{TM}=4\text{A}$, Fig. 4	-	-	1.5	V
I_{DRM} / I_{RRM}	Repetitive peak off-state current	$V_D=V_{DRM}/V_{RRM}$, $T_j=25^\circ\text{C}$	-	-	5	μA
		$V_D=V_{DRM}/V_{RRM}$, $T_j=110^\circ\text{C}$	-	-	100	μA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th} (j-c)$	Junction to case (AC)	7.2	$^\circ\text{C/W}$
$R_{th} (j-a)$	Junction to ambient	100	$^\circ\text{C/W}$

PART NUMBER



CHARACTERISTICS CURVES

FIG.1: Maximum power dissipation versus RMS on-state current (full cycle)

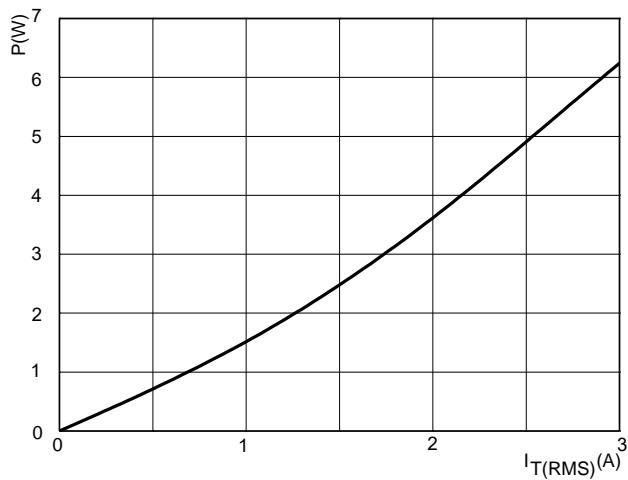


FIG.2: RMS on-state current versus case temperature (full cycle)

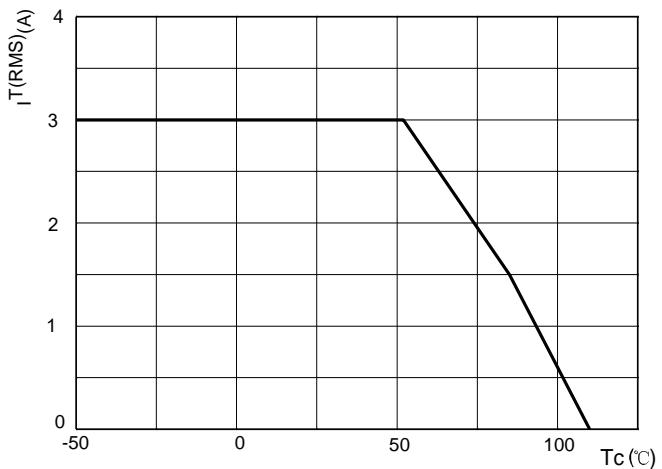


FIG.3: Surge peak on-state current versus number of cycles

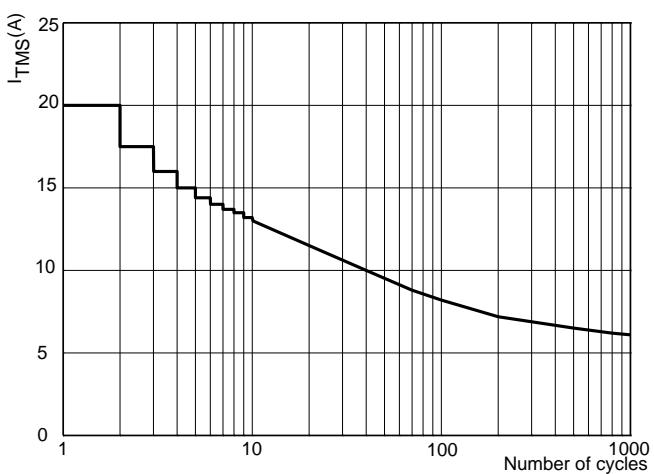


FIG.4: On-state characteristics (maximum values)

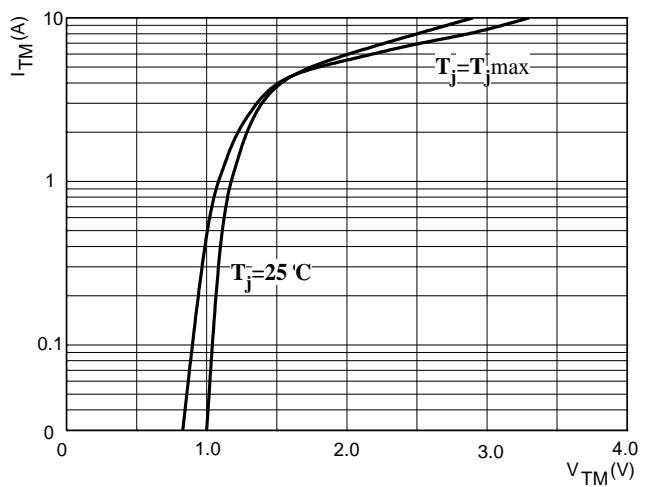


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10ms$

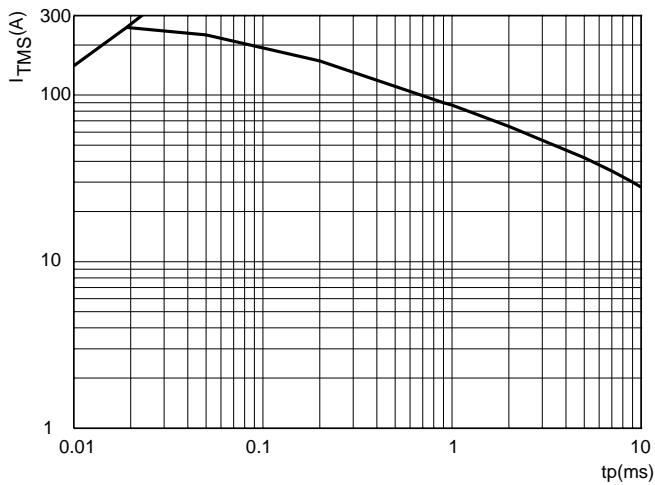
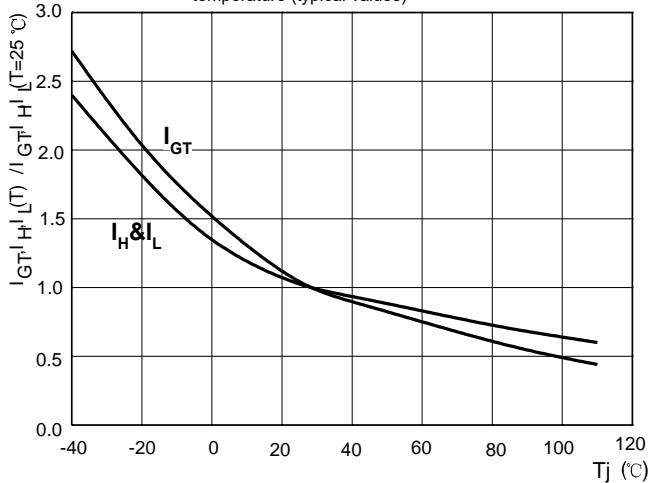
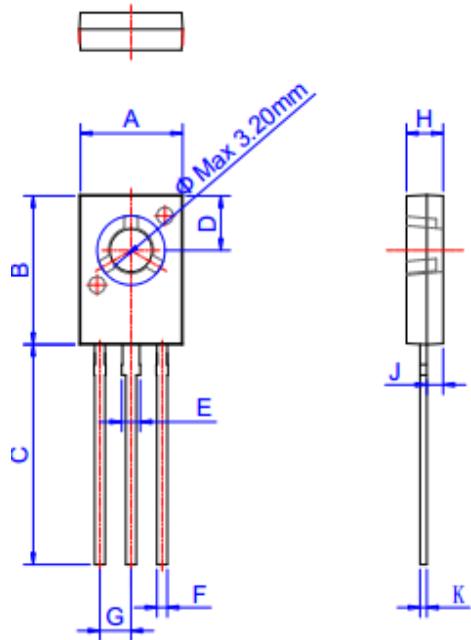


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature (typical values)



TO-126K PACKAGE OUTLINE DIMENSIONS



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	10.6		11.2	0.417		0.441
C	15.3		16.3	0.602		0.642
D	3.90		4.10	0.154		0.161
E	1.17		1.47	0.046		0.058
F	0.66		0.86	0.026		0.034
G		2.29			0.090	
H	2.50		2.90	0.098		0.114
J	1.10		1.50	0.043		0.059
K	0.45		0.60	0.018		0.024